



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS56033-LBA		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA001141734						
<b>Package</b>		PG-TSON-24-3		<b>Weight*</b>		181.12 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.920	3.27	3.27	32688	32688
leadframe	inorganic material	phosphorus	7723-14-0	0.021	0.01		116	
	non noble metal	zinc	7440-66-6	0.084	0.05		465	
	non noble metal	iron	7439-89-6	1.685	0.93		9304	
wire	non noble metal	copper	7440-50-8	68.425	37.78	38.77	377793	387678
	non noble metal	copper	7440-50-8	1.663	0.92	0.92	9183	9183
	encapsulation	organic material	carbon black	1333-86-4	0.192	0.11		1057
plastics	plastics	epoxy resin	-	9.862	5.45		54453	
	inorganic material	silicondioxide	60676-86-0	85.697	47.30	52.86	473152	528662
leadfinish	non noble metal	tin	7440-31-5	2.547	1.41	1.41	14060	14060
plating	noble metal	silver	7440-22-4	0.378	0.21	0.21	2087	2087
solder	noble metal	silver	7440-22-4	0.116	0.06		641	
	non noble metal	tin	7440-31-5	0.093	0.05		513	
	non noble metal	lead	7439-92-1	4.435	2.45	2.56	24488	25642
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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